

# **DELO<sup>®</sup> MONOPOX EG2596**

### modified epoxy resin | 1C | heat-curing

free of solvents | flow-resistant, thixotropic, reflow-resistant

# **Special features of product**

- compliant with RoHS Directive 2015/863/EU
- halogen-free according to IEC 61249-2-21
- compliant with limits of VOC content in adhesive acc. to GB33372-2020

# **Typical area of use** -40 - 180 °C

### Curing

Typical curing time		
at +130 °C in air convection oven	10	min
at +90 °C in air convection oven	90	min

# Processing

Typical adhesive application	stencil printing, screen printing, jetting, needle dispensing		
Conditioning time (typical)			
when stored in cold conditions in containers up to 10 ml	0.5	h	
when stored in cold conditions in containers up to 50 ml	1	h	
Processing time			
in standard climate +23 °C / 50 % r. h.	7	d	
Storage life in unopened original container			
at -18 °C	6	month(s)	

### Function

electronic adhesive



Technical properties		
Color in uncured condition	red	
Fluorescence	fluorescent	
Parameters		
Density by the criteria of DIN 66137-2   liquid	1.16	g/cm³
Viscosity liquid   Rheometer   Shear rate: 10 1/s   Gap: 500 μm	65000	mPa∙s
Thixotropy index liquid   Rheometer   Gap: 500 μm	8.6	
Compression shear strength DELO Standard 5   <b>AI</b>   <b>AI</b>   Pretreatment: sand-blasted   130 °C   20 min	50	MPa
Compression shear strength DELO Standard 5   <b>FR4</b>   <b>FR4</b>   Pretreatment: Annealing   130 °C   20 min	52	MPa
Compression shear strength DELO Standard 5   <b>PA6</b>   Pretreatment: Annealing   130 °C   20 min	20	MPa
Die shear strength DELO Standard 30   <b>Si</b>   Chip 1 mm x 1 mm   <b>Au</b>   25 mm x 15 mm   Pretreatment: Annealing   130 °C   20 min	55	N
Die shear strength DELO Standard 30   <b>Si</b>   Chip 1 mm x 1 mm   <b>FR4</b>   Tape   Pretreatment: Annealing   130 °C   20 min	65	Ν
Die shear strength DELO Standard 30   <b>Si</b>   Chip 1 mm x 1 mm   <b>FR4</b>   20 mm x 20 mm x 5 mm   Pretreatment: Annealing   130 °C   20 min	90	N
Die shear strength DELO Standard 30   <b>Si</b>   Chip 1 mm x 1 mm   <b>Ni</b>   25 mm x 15 mm   Pretreatment: Annealing   130 °C 20 min	56 /	N
Tensile strength by the criteria of DIN EN ISO 527   130 °C   20 min	54	MPa
Elongation at tear by the criteria of DIN EN ISO 527   130 °C   20 min	3	%
Young's modulus <i>liquid   DMTA</i>	2100	MPa
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Shore hardness D by the criteria of DIN EN ISO 868   130 °C   20 min	79	
Glass transition temperature DMTA   130 °C   20 min	115	°C
Coefficient of linear expansion DELO Standard 26   TMA   Evaluation T: -35 °C - 50 °C   130 °C   20 min	65	ppm/K
Coefficient of linear expansion DELO Standard 26   TMA   Evaluation T: 125 °C - 200 °C   130 °C   20 min	181	ppm/K
Shrinkage 130 °C   20 min	1.0	vol. %
Water absorption by the criteria of DIN EN ISO 62   Layer thickness: 4 mm   130 °C   20 min   Type of storage: Media   Medium: Distilled water   Storage temperature: at approx. +23 °C   Duration: 24 h	0.2	wt. %
Converting table		
°F = (°C x 1.8) + 32 1 MPa = 145.04 psi		

F	$-(0 \times 1.0) + 32$	i ivira	- 145.04 psi
1 inch	= 25.4 mm	1 GPa	= 145.04 ksi
1 mil	= 25.4 µm	1 cP	= 1 mPa·s
1 oz	= 28.3495 g	1 N	= 0.225 lb

# General curing and processing information

The curing time stated in the technical data was determined in the laboratory. It can vary depending on the adhesive quantity and component geometry and is therefore a reference value. The heating time of the components must be added to the actual curing time. It depends on component size and type of heat input. The specified curing temperature must be reached directly at the adhesive. Increasing or decreasing the curing temperature and / or irradiation intensity and / or irradiation time shortens or prolongs the curing time and can lead to changed physical properties. Depending on the adhesive quantity used, exothermic reaction heat is generated which can lead to overheating. In this case, a lower curing temperature is to be selected. Values measured after 24 h at approx. 23 °C / 50 % r.h., unless otherwise specified.

#### General

The data and information provided are based on tests performed under laboratory conditions. Reliable information about the behavior of the product under practical conditions and its suitability for a specific purpose cannot be concluded from this. It is the customer's responsibility to test the suitability of a product for the intended purpose by considering all specific requirements and by applying standards the customer deems suitable (e. g. DIN 2304-1). Type, physical and chemical properties of the materials to be processed with the product, as well as all actual influences occurring during transport, storage, processing and use, may cause deviations in the behavior of the product compared to its behavior under laboratory conditions. All data provided are typical average values or uniquely determined parameters measured under laboratory conditions. The data and information provided are therefore no guarantee for specific product properties or



the suitability of the product for a specific purpose.

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All products provided by DELO are subject to DELO's General Terms of Business. Verbal ancillary agreements are deemed not to exist.

#### Instructions for use

You can find further details in the instructions for use.

The instructions for use are available on www.DELO-adhesives.com.

We will be pleased to send them to you on demand.

#### Occupational health and safety

See material safety data sheet.

#### Specification

Nothing contained in this Technical Datasheet shall be interpreted as any express warranty or guarantee. This Technical Datasheet is for reference only and does not constitute a product specification. Please ask our responsible Sales Engineer for the applicable product specification which includes defined ranges. DELO is neither liable for any values and content of this Technical Datasheet nor for oral or written recommendations regarding the use, unless otherwise agreed in writing. This limitation of liability is not applicable for damages resulting from intent, gross negligence or culpable breach of cardinal obligations, nor shall it apply in case of death or personal injury or in case of liability under any applicable compulsory law.

